レイヤーパッケージ(事)技術部設計係

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2.10.12
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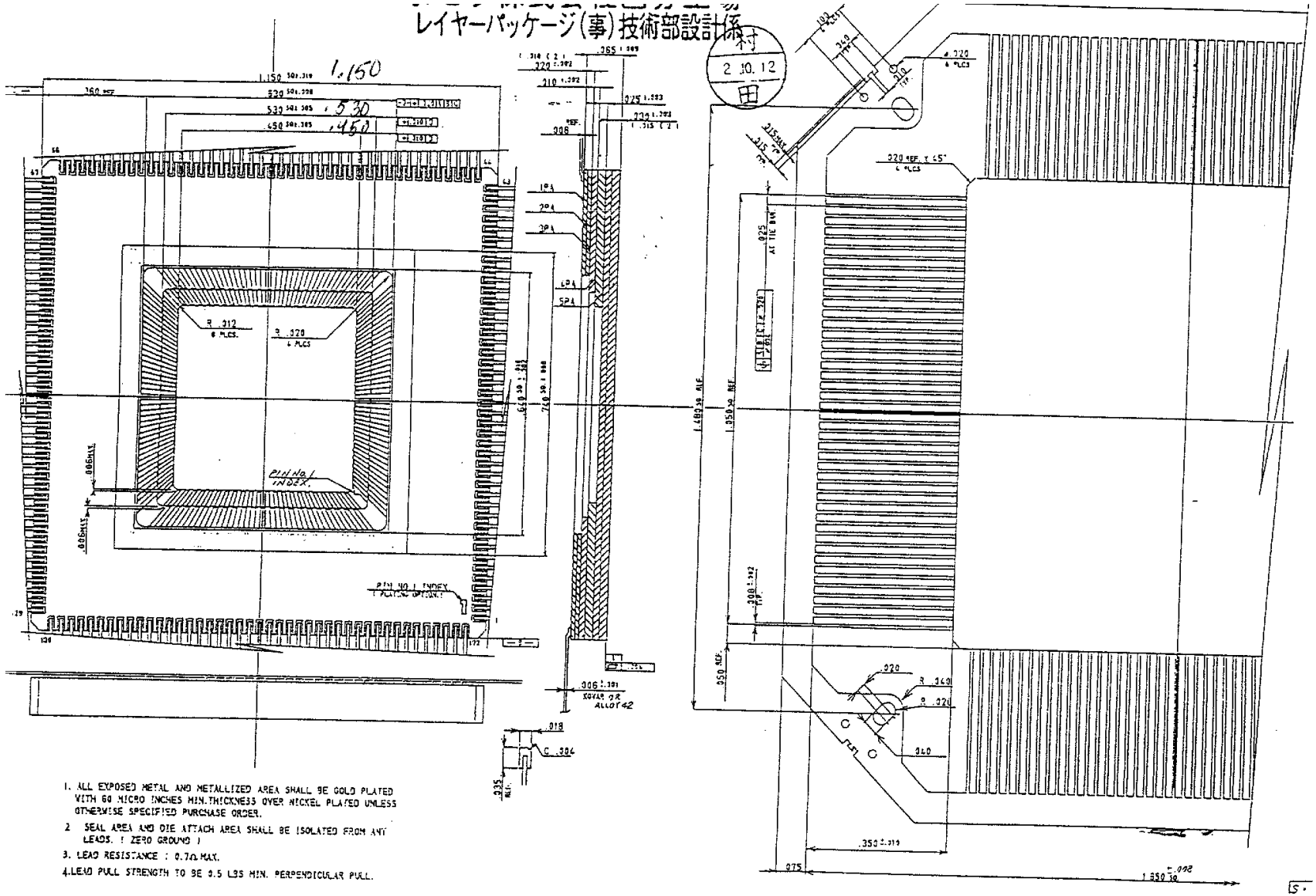

1. ALL EXPOSED METAL AND METALLIZED AREA SHALL BE GOLD PLATED WITH 60 MICRO INCHES MIN.THICKNESS OVER NICKEL PLATED UNLESS OTHERWISE SPECIFIED PURCHASE ORDER.
2. SEAL AREA AND DIE ATTACH AREA SHALL BE ISOLATED FROM ANY LEADS. (ZERO GROUND)
3. LEAD RESISTANCE : 0.7Ω MAX.
4. LEAD PULL STRENGTH TO BE 0.5 LBS MIN. PERPENDICULAR PULL.